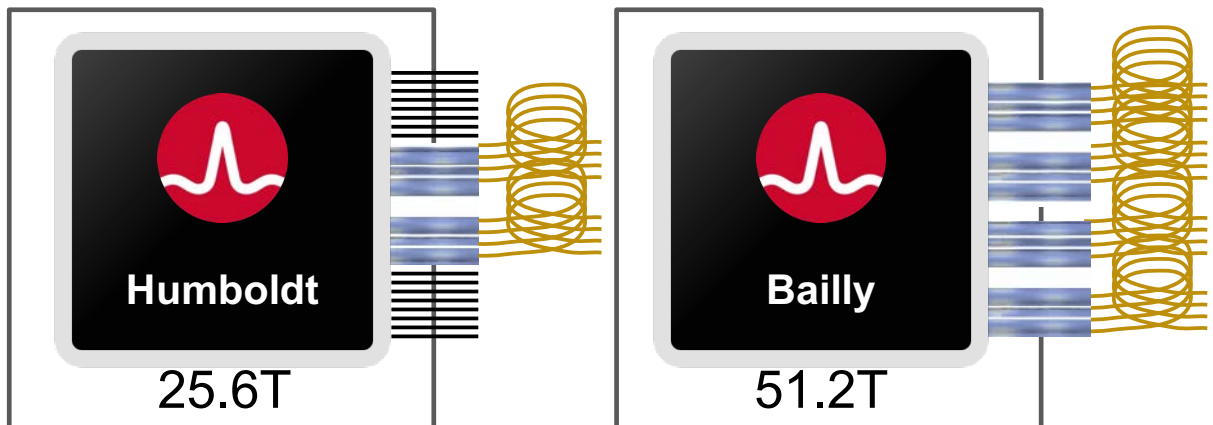


SILICON PHOTONICS AND CO-PACKAGED OPTICS

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Abstract

This report provides an in-depth analysis of the impact of silicon photonics (SiP) on the market for optical transceivers and related components in 2016-2021. It also presents a forecast for shipments and sales of discrete and integrated products based on InP, GaAs, SiP and LiNbO₃ technologies for 2022–2027. The forecast is segmented by main applications, including Ethernet, WDM, Wireless Fronthaul/Backhaul, Fibre Channel, FTTx, Active Optical Cables (AOCs), Embedded Optical Modules (EOMs) and Co-Packaged Optics (CPO). Products are sorted by data rate, reach, and form factor into more than 150 categories. The report also discusses the supply chain for SiP products, including profiles of the leading foundries.

Adoption of CPO is discussed in detail, including use cases in datacenters, AI Clusters and HPCs.

LightCounting is a market research company focused on the in-depth study of high-speed interconnects for the datacom, telecom, and consumer communications markets. Our research covers the whole supply chain from optical and semiconductor components, to modules, sub-systems and their applications in telecom and datacom systems.

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LightCounting Market Research

7726 Gunston Plaza, Unit 1480, Lorton, VA 22199

www.lightcounting.com | 408-962-4851